

# MOSFET - Power, Single N-Channel, SUPERFET<sup>®</sup> V, FRFET<sup>®</sup>, TO220 600 V, 125 mΩ, 22 A

# NTP125N60S5FZ

#### **Description**

The SUPERFET V MOSFET FRFET series, optimized reverse recovery performance of body diode, can remove additional component and improve system reliability for soft switching applications such as PSFB and LLC.

#### Features

- $650 \text{ V} @ \text{T}_{\text{J}} = 150^{\circ}\text{C}$
- Typ.  $R_{DS(on)} = 100 \text{ m}\Omega$
- 100% Avalanche Tested
- Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

#### **Applications**

- Telecom / Server Power Supplies
- EV Charger / UPS / Solar / Industrial Power Supplies

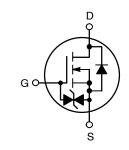
#### ABSOLUTE MAXIMUM RATINGS (T<sub>J</sub> = 25°C, Unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain-to-Source Voltage		$V_{DSS}$	600	V
Gate-to-Source Voltage	DC	$V_{GSS}$	±20	V
	AC (f > 1 Hz)		±20	
Continuous Drain Current	T <sub>C</sub> = 25°C	I <sub>D</sub>	22	Α
	T <sub>C</sub> = 100°C	l	13	
Power Dissipation	T <sub>C</sub> = 25°C	P <sub>D</sub>	156	W
Pulsed Drain Current (Note 1)	T <sub>C</sub> = 25°C	I <sub>DM</sub>	81	Α
Pulsed Source Current (Body Diode) (Note 1)	T <sub>C</sub> = 25°C	I <sub>SM</sub>	81	Α
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C
Source Current (Body Diode)		Is	22	Α
Single Pulse Avalanche Energy	$I_L = 4.5 \text{ A},$ $R_G = 25 \Omega$	E <sub>AS</sub>	184	mJ
Avalanche Current		I <sub>AS</sub>	4.5	Α
Repetitive Avalanche Energy (Note 1)		E <sub>AR</sub>	1.56	mJ
MOSFET dv/dt		dv/dt	120	V/ns
Peak Diode Recovery dv/dt (Note 2)			70	
Lead Temperature for Soldering Purposes (1/8" from case for 10 seconds)		T <sub>L</sub>	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

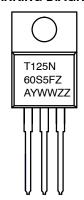
- 1. Repetitive rating: pulse-width limited by maximum junction temperature.
- 2.  $I_{SD} \le 11$  A, di/dt  $\le 200$  A/ $\mu$ s,  $V_{DD} \le 400$  V, starting  $T_J = 25^{\circ}C$ .

V <sub>DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX	
600 V	125 m $\Omega$ @ 10 V	22 A	





#### MARKING DIAGRAM



T125N60S5FZ = Specific Device Code
A = Assembly Plant Code
YWW = Date Code (Year & Week)
ZZ = Lot

#### **ORDERING INFORMATION**

Device	Package Shipping	
NTP125N60S5FZ	TO220	50 Units / Tube

#### THERMAL CHARACTERISTICS

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case, Max.	$R_{ heta JC}$	0.8	°C/W
Thermal Resistance, Junction-to-Ambient, Max.	$R_{ hetaJA}$	62.5	

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V, I}_{D} = 1 \text{ mA, T}_{J} = 25^{\circ}\text{C}$	600	_	-	٧
Drain-to-Source Breakdown Voltage Temperature Coefficient	$\Delta V_{(BR)DSS}/ \Delta T_J$	I <sub>D</sub> = 10 mA, Referenced to 25°C	-	630	-	mV/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 600 \text{ V}, T_J = 25^{\circ}\text{C}$	_	-	10	μΑ
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±2	μΑ
ON CHARACTERISTICS						-
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 11 A, T <sub>J</sub> = 25°C	-	100	125	mΩ
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{GS} = V_{DS}, I_D = 2.2 \text{ mA}, T_J = 25^{\circ}\text{C}$	3.2	-	4.8	٧
Forward Trans-conductance	9FS	V <sub>DS</sub> = 20 V, I <sub>D</sub> = 11 A	-	23	-	S
CHARGES, CAPACITANCES & GATE I	RESISTANCE			-		•
Input Capacitance	C <sub>ISS</sub>	$V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{ V}, f = 250 \text{ kHz}$	_	2213	_	pF
Output Capacitance	C <sub>OSS</sub>		-	34	-	
Time Related Output Capacitance	C <sub>OSS(tr.)</sub>	$I_D$ = Constant, $V_{DS}$ = 0 V to 400 V, $V_{GS}$ = 0 V	-	520	-	
Energy Related Output Capacitance	C <sub>OSS(er.)</sub>	V <sub>DS</sub> = 0 V to 400 V, V <sub>GS</sub> = 0 V	-	56	-	
Total Gate Charge	Q <sub>G(tot)</sub>	V <sub>DD</sub> = 400 V, I <sub>D</sub> = 11 A, V <sub>GS</sub> = 10 V	-	39	-	nC
Gate-to-Source Charge	$Q_{GS}$		_	12	-	
Gate-to-Drain Charge	$Q_{GD}$		-	11	-	
Gate Resistance	$R_{G}$	f = 1 MHz	-	8	-	Ω
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	t <sub>d(on)</sub>	$V_{GS} = 0/10 \text{ V}, V_{DD} = 400 \text{ V},$	-	31	-	ns
Rise Time	t <sub>r</sub>	$I_D = 11 \text{ A, } R_G = 7.5 \Omega$	-	14	-	1
Turn-Off Delay Time	t <sub>d(off)</sub>		-	86	-	7
Fall Time	t <sub>f</sub>		-	7	-	1
SOURCE-TO-DRAIN DIODE CHARAC	TERISTICS					
Forward Diode Voltage	$V_{SD}$	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 11 A, T <sub>J</sub> = 25°C	-	-	1.2	V
Reverse Recovery Time	t <sub>RR</sub>	V <sub>GS</sub> = 0 V, I <sub>SD</sub> = 11 A,	-	89	_	ns
Reverse Recovery Charge	Q <sub>RR</sub>	dl/dt = 100 A/μs, V <sub>DD</sub> = 400 V	_	440	_	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### **TYPICAL CHARACTERISTICS**

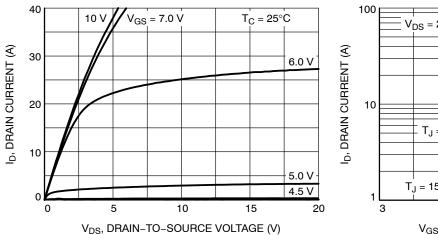
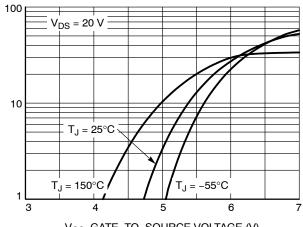


Figure 1. On-Region Characteristics



V<sub>GS</sub>, GATE-TO-SOURCE VOLTAGE (V) Figure 2. Transfer Characteristics

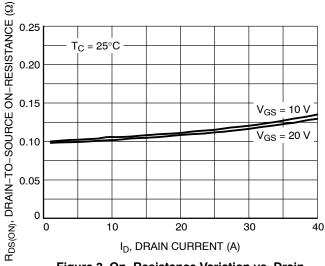


Figure 3. On–Resistance Variation vs. Drain Current and Gate Voltage

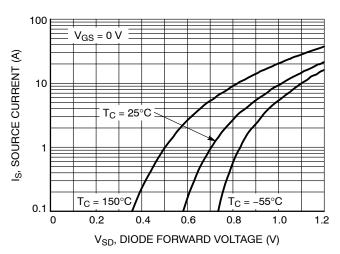


Figure 4. Diode Forward Voltage vs. Source Current

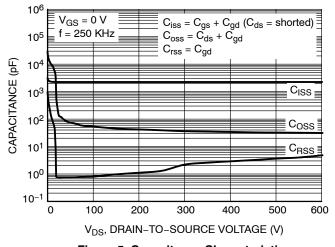


Figure 5. Capacitance Characteristics

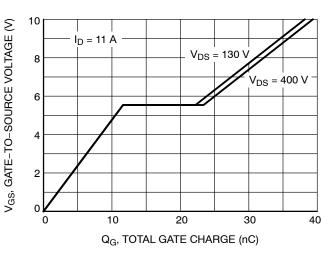


Figure 6. Gate Charge Characteristics

#### **TYPICAL CHARACTERISTICS**

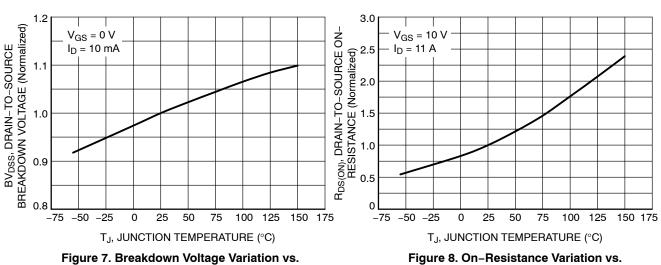


Figure 7. Breakdown Voltage Variation vs. Temperature

ID, DRAIN CURRENT (A)

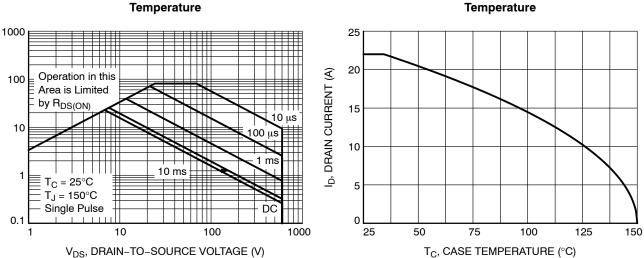
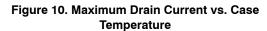


Figure 9. Maximum Safe Operating Area



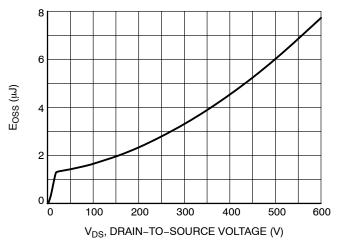


Figure 11.  $E_{OSS}$  vs. Drain-to-Source Voltage

#### **TYPICAL CHARACTERISTICS**

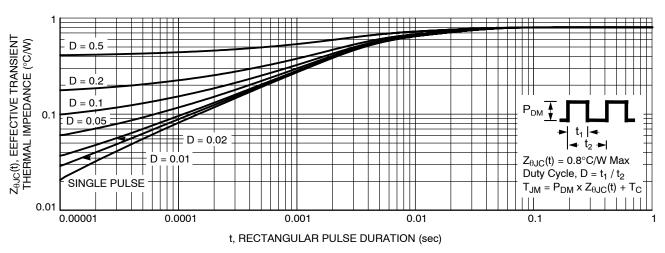


Figure 12. Transient Thermal Impadance

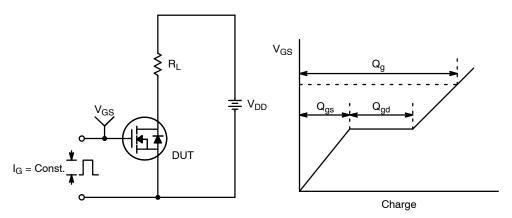


Figure 13. Gate Charge Test Circuit & Waveform

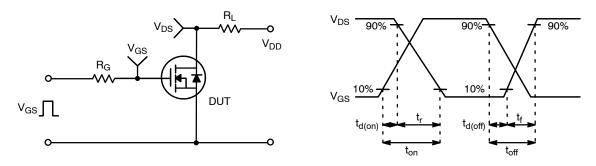


Figure 14. Resistive Switching Test Circuit & Waveforms

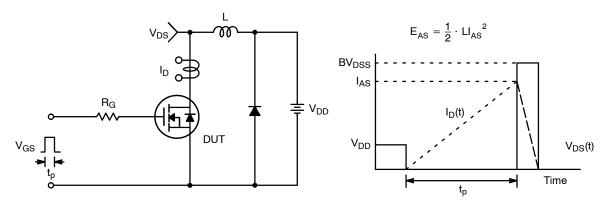


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

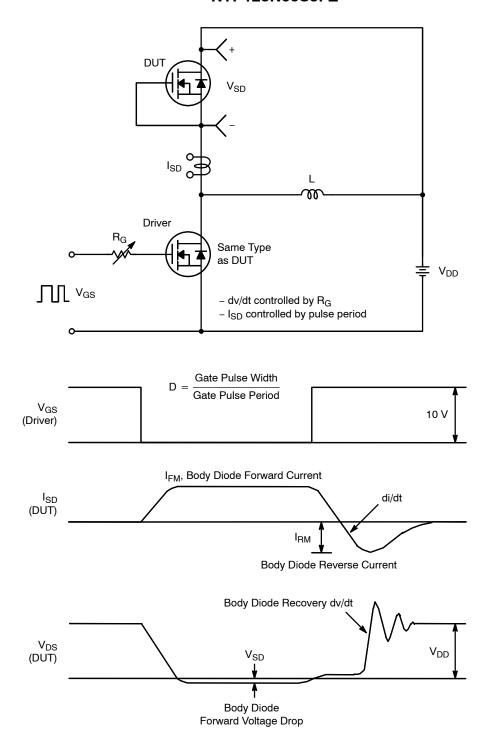
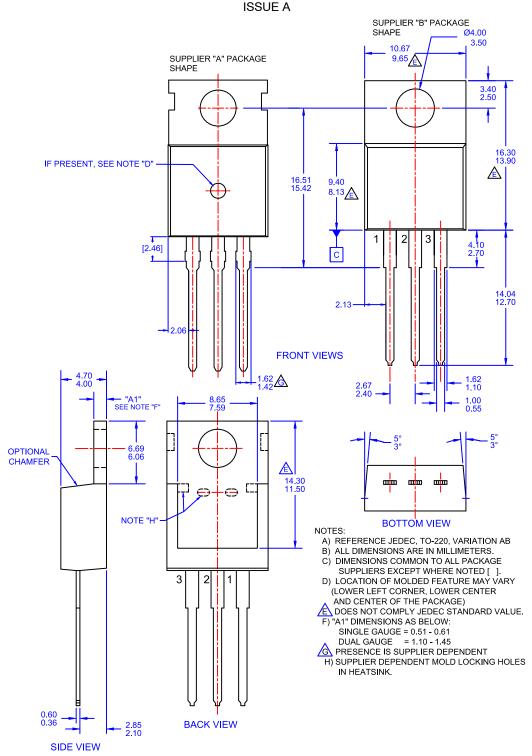


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

#### **PACKAGE DIMENSIONS**

## TO-220-3LD CASE 340AT



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